

Title (en)

METHOD FOR ACTIVATING AT LEAST ONE SURFACE, ACTIVATION COMPOSITION, AND USE OF THE ACTIVATION COMPOSITION TO ACTIVATE A SURFACE FOR ELECTROLESS PLATING

Title (de)

VERFAHREN ZUR AKTIVIERUNG VON MINDESTENS EINER OBERFLÄCHE, AKTIVIERUNGSZUSAMMENSETZUNG UND VERWENDUNG DER AKTIVIERUNGSZUSAMMENSETZUNG ZUR AKTIVIERUNG EINER OBERFLÄCHE ZUR STROMLOSEN PLATTIERUNG

Title (fr)

PROCÉDÉ D'ACTIVATION D'AU MOINS UNE SURFACE, COMPOSITION D'ACTIVATION ET UTILISATION DE LA COMPOSITION D'ACTIVATION POUR ACTIVER UNE SURFACE DE DÉPÔT AUTOCATALYTIQUE

Publication

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Application

**EP 19219076 A 20191220**

Priority

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Abstract (en)

The present invention is directed to a method for activating at least one surface of a substrate, the method comprising the steps a) providing the substrate having the at least one surface; b) optionally, pretreating the at least one surface of the substrate with a pretreating composition; c) optionally, conditioning the at least one surface of the substrate with a conditioning composition; d) contacting the at least one surface of the substrate with an activation composition comprising i) copper ions; and ii) at least one unsubstituted or substituted N-heteroaromatic compound; e) contacting the at least one surface of the substrate obtained after step d) with a reducing agent containing composition such that copper ions are reduced to metallic copper on said surface and thereby activating the at least one surface of the substrate.

IPC 8 full level

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CPC (source: EP)

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Citation (applicant)

- US 2008038450 A1 20080214 - POOLE MARK A [US], et al
- WO 2013050332 A2 20130411 - ATOTECH DEUTSCHLAND GMBH [DE]

Citation (search report)

- [XYI] EP 3287465 A1 20180228 - LCY CHEMICAL CORP [TW]
- [Y] US 4248632 A 19810203 - EHRICH HANS J, et al
- [XI] EP 0381873 A2 19900816 - KEMIFAR SPA [IT]

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